

SHIELDED SEMICONDUCTOR PACKAGE WITH SINGLE-SIDED SUBSTRATE  
AND METHOD FOR MAKING THE SAME

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ABSTRACT

A semiconductor chip package is disclosed. The package includes a substrate, a metallization layer formed on one side of the substrate and a semiconductor die mounted on the substrate. The semiconductor die is electrically connected to a portion of the metallization layer. A shield element is mounted on the substrate and electrically connected to a portion of the metallization layer. A package mold surrounds the semiconductor die and the shield element.

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